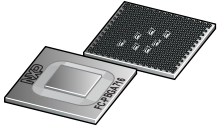


# SOT2202-1

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 1.455 mm body

24 April 2026

Package information



## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	FC-PBGA716
<b>Package style descriptive code</b>	FC-PBGA (flip chip - plastic ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-12-2025
<b>Manufacturer package code</b>	98ASA02036D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	18.9	19	19.1	mm
package width	18.9	19	19.1	mm
seated height	1.295	1.455	1.625	mm
nominal pitch	-	0.7	-	mm
actual quantity of termination	-	716	-	



FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 1.455 mm body

2 Package outline

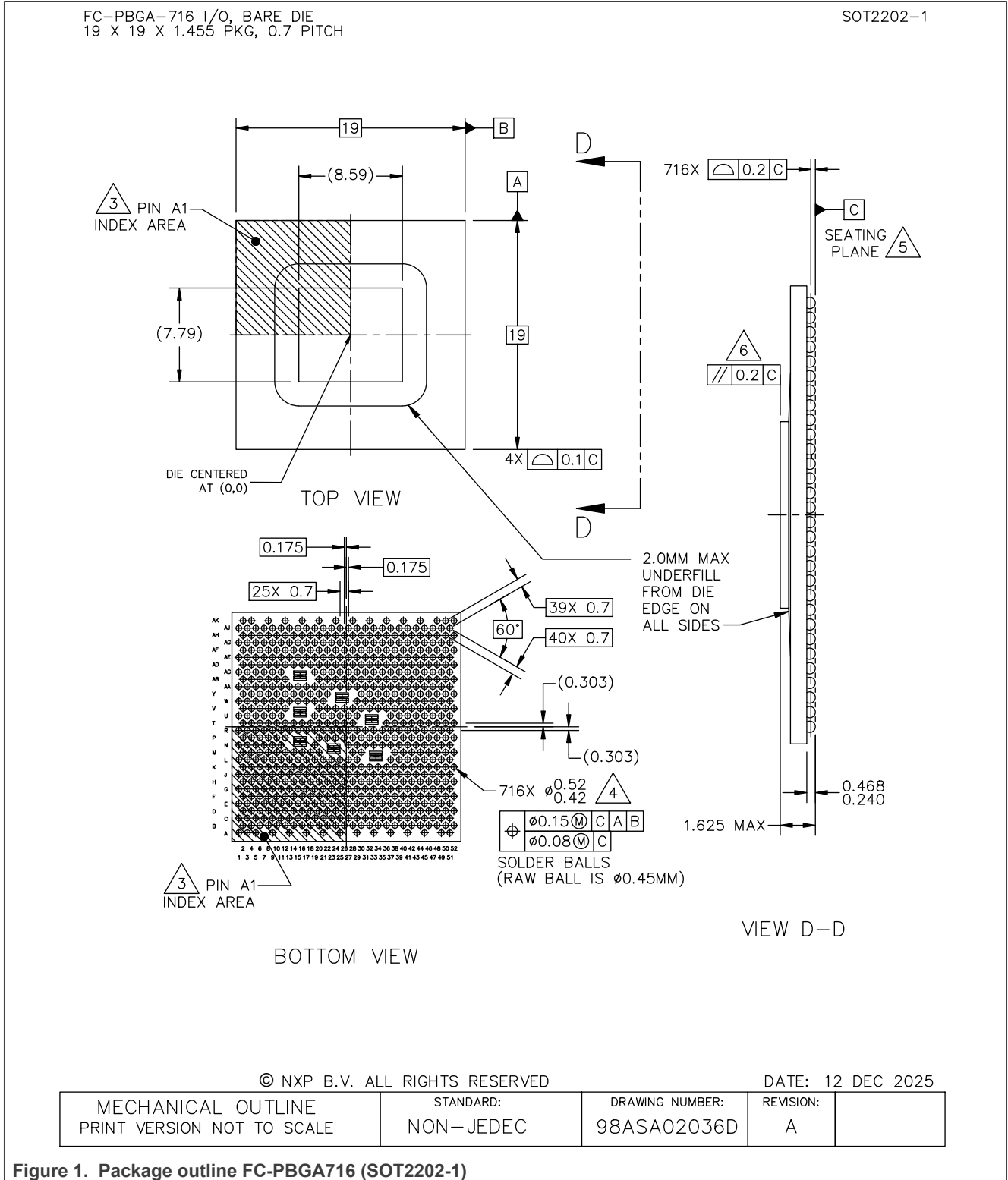
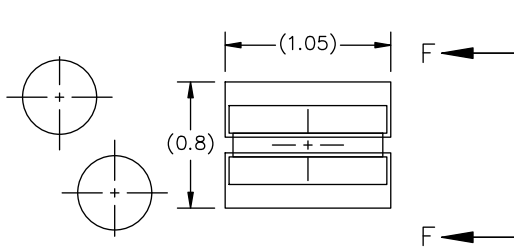
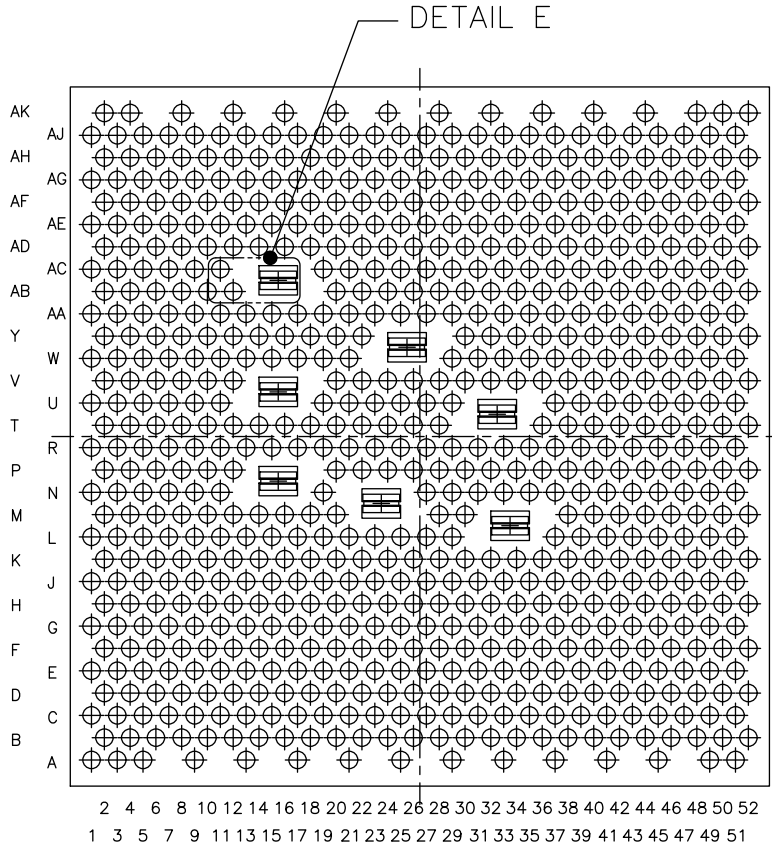


Figure 1. Package outline FC-PBGA716 (SOT2202-1)

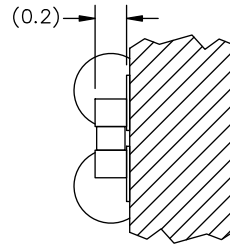
FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 1.455 mm body

FC-PBGA-716 I/O, BARE DIE  
19 X 19 X 1.455 PKG, 0.7 PITCH

SOT2202-1



DETAIL E



VIEW F-F  
CAPACITOR DETAIL  
APPLIES 7 PLACES

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DATE: 12 DEC 2025

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA02036D	REVISION: A	
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Figure 2. Package outline detail E of FC-PBGA716 (SOT2202-1)

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 1.455 mm body

3 Soldering

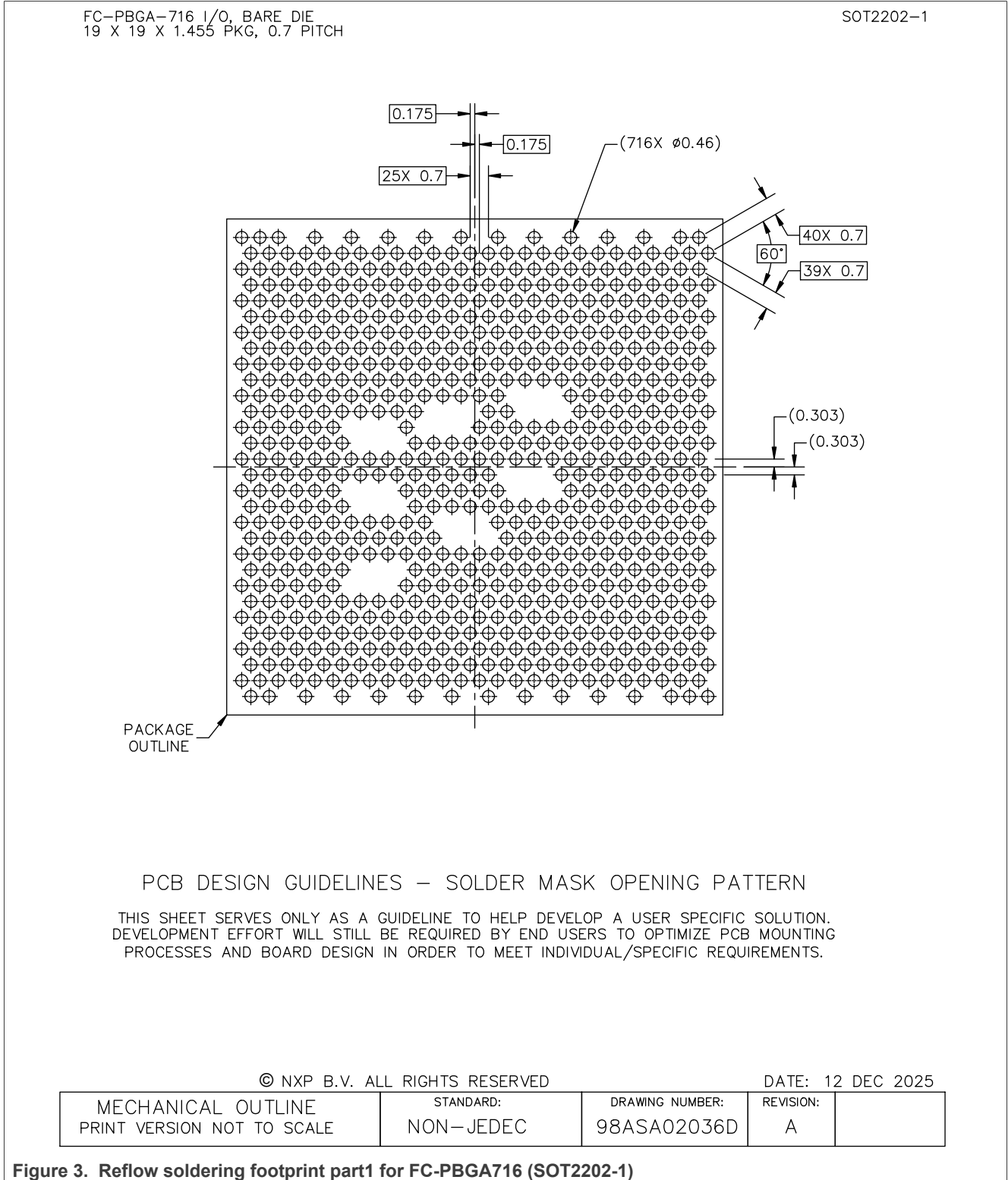


Figure 3. Reflow soldering footprint part1 for FC-PBGA716 (SOT2202-1)

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 1.455 mm body

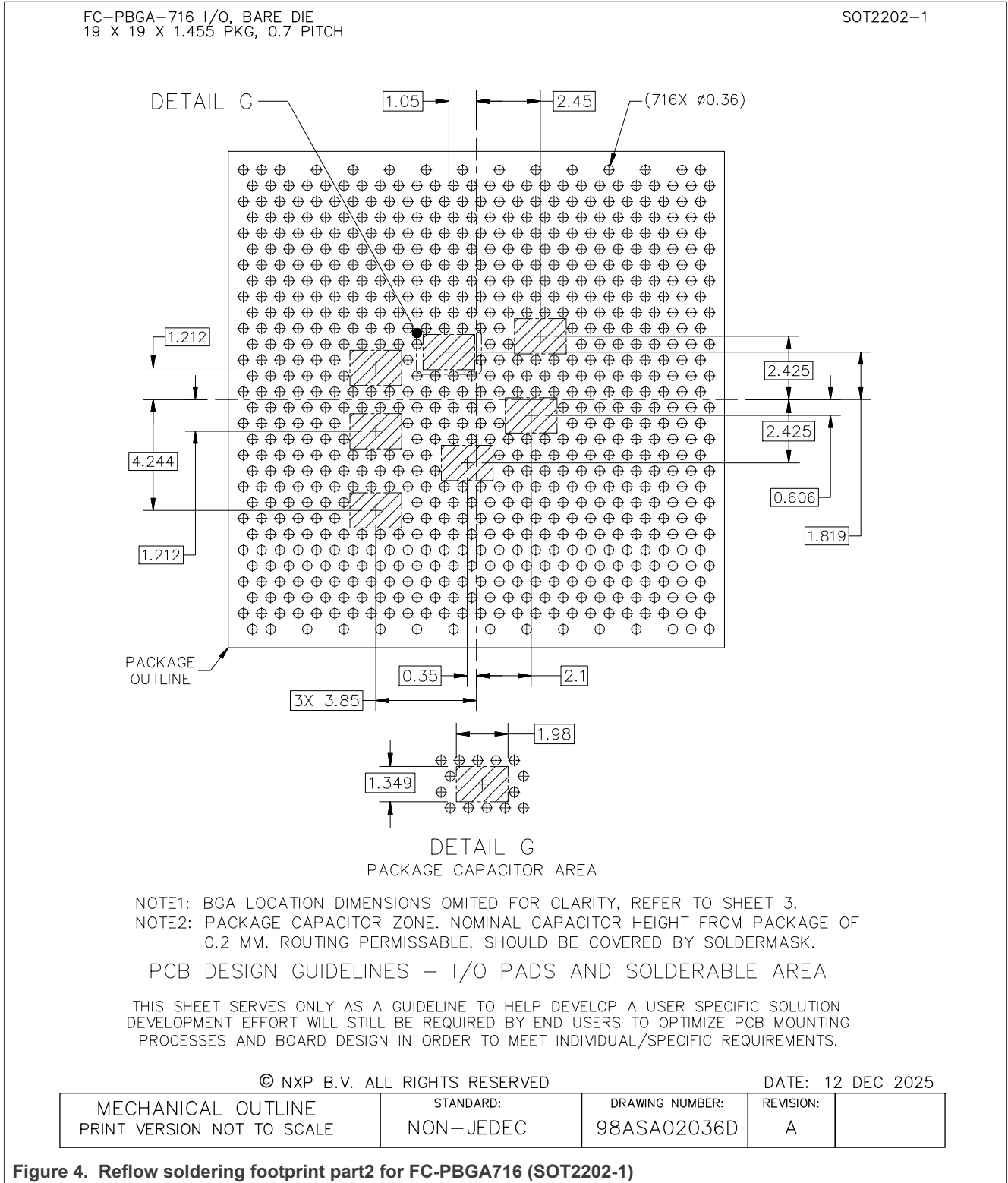
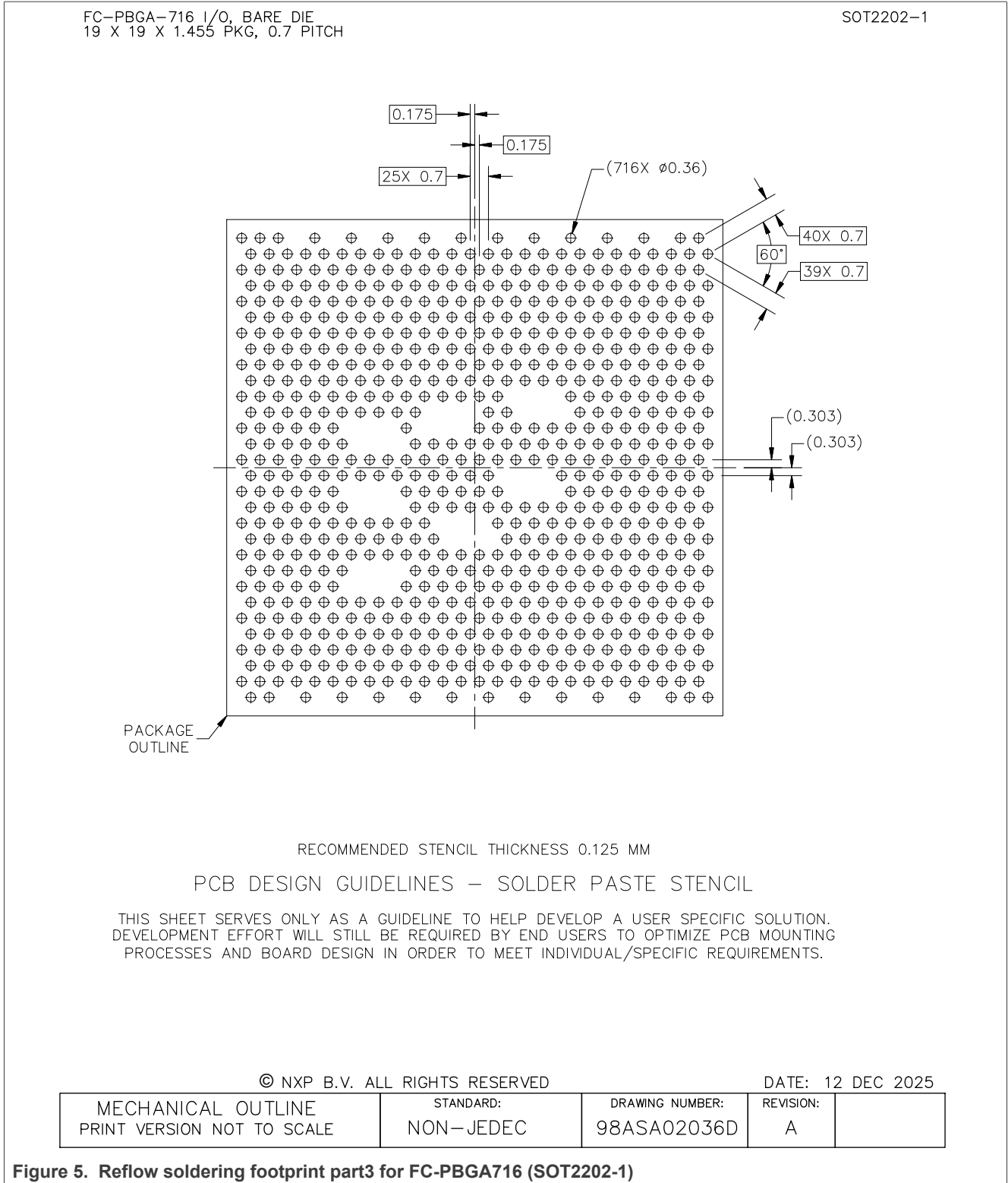


Figure 4. Reflow soldering footprint part2 for FC-PBGA716 (SOT2202-1)

FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 1.455 mm body



FC-PBGA716, flip chip - plastic ball grid array, 716 terminals, 0.7 mm pitch, 19 mm x 19 mm x 1.455 mm body

FC-PBGA-716 I/O, BARE DIE  
19 X 19 X 1.455 PKG, 0.7 PITCH

SOT2202-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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Figure 6. Package outline note FC-PBGA716 (SOT2202-1)

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